onsemi

Regulator - TinyPower[™], Buck-Boost, 2.5 A, I²C FAN49103

Description

The FAN49103 is a high efficiency buck-boost switching mode regulator which accepts input voltages either above or below the regulated output voltage. Using full- bridge architecture with synchronous rectification, the FAN49103 is capable of delivering up to 2.5 A while regulating the output at 3.4 V. The FAN49103 exhibits seamless transition between step-up and step-down modes reducing output disturbances. The output voltage and operation mode of the regulator can be programmed through an I²C interface.

At moderate and light loads, Pulse Frequency Modulation (PFM) is used to operate the device in power-save mode to maintain high efficiency. In PFM mode, the part still exhibits excellent transient response during load steps. At moderate to heavier loads or Forced PWM mode, the regulator switches to PWM fixed-frequency control. While in PWM mode, the regulator operates at a nominal fixed frequency of 1.8 MHz, which allows for reduced external component values.

The FAN49103 is available in a 20-bump 1.615 mm x 2.15 mm with 0.4 mm pitch WLCSP.

Features

- 24 µA Typical PFM Quiescent Current
- Above 95% Efficiency
- Total Layout Area = 11.61 mm^2
- Input Voltage Range: 2.5 V to 5.5 V
- Maximum Continuous Load Current:
 - 3.0 A at V_{OUT} = 3.4 V, V_{IN} = 3.3 V
 - 2.5 A at $V_{OUT} = 3.4 \text{ V}$, $V_{IN} = 3.0 \text{ V}$
 - 2.0 A at V_{OUT} = 3.4 V, V_{IN} = 2.5 V
- I²C Compatible Interface
- Programmable Output Voltage:
 2.8 V to 4.0 V in 25 mV Steps
- 1.8 MHz Fixed-Frequency Operation in PWM Mode
- Automatic / Seamless Step-up and Step-down Mode Transitions
- Forced PWM and Automatic PFM/PWM Mode Selection
- 0.5 µA Typical Shutdown Current
- Low Quiescent Current Pass-Through Mode
- Internal Soft-Start and Output Discharge
- Low Ripple and Excellent Transient Response
- Internally Set, Automatic Safety Protections (UVLO, OTP, SCP, OCP)
- Package: 20 Bump, 0.4 mm Pitch WLCSP

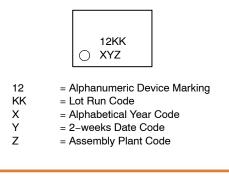
Applications

- Smart Phones
- Tablets, Netbooks, Ultra-Mobile PCs
- Portable Devices with Li-ion Battery
- 2G/3G/4G Power Amplifiers
- NFC Applications



WLCSP20 2.015x1.615x0.586 CASE 567QK

MARKING DIAGRAM



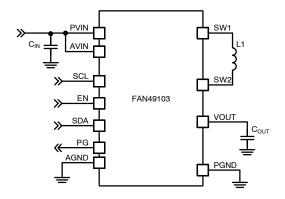


Figure 1. Typical Application

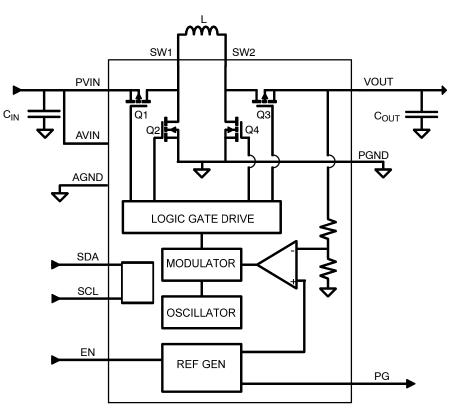
ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ORDERING INFORMATION

Part Number	Default VOUT	Output Discharge	Slave Address	Temperature Range	Package	Packing Method [†]	Device Marking
FAN49103AUC340X	3.4 V	Yes	7h'70	–40 to 85°C	20–Ball (WLCSP)	Tape and Reel	FF
FAN49103AUC330X	3.3 V	Yes	7h'70	–40 to 85°C	20-Ball (WLCSP)	Tape and Reel	КX
FAN49103AUC34AX (In Development)	3.4 V	Yes	7h'71	–40 to 85°C	20-Ball (WLCSP)	Tape and Reel	TBD

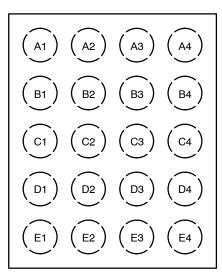
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



BLOCK DIAGRAM

Figure 2. Block Diagram

PIN CONFIGURATION





PIN DEFINITIONS (Note 1)

Pin #	Name	Description
A3, A4	PVIN	Power Input Voltage. Connect to input power source. Connect to CIN with minimal path
A1	AVIN	Analog Input Voltage. Analog input for device. Connect to CIN and PVIN
A2	EN	Enable. A HIGH logic level on this pin forces the device to be enabled. A LOW logic level forces the device into shutdown. EN pin can be tied to VIN or driven via a GPIO logic voltage
B3, B4	SW1	Switching Node 1. Connect to inductor L1
E1	AGND	Analog Ground. Control block signal is referenced to this pin. Short AGND to PGND at GND pad of COUT
B1, C1, C2, C3, C4, D1	PGND	Power Ground. Low-side MOSFET of buck and main MOSFET of boost are referenced to this pin. C_{IN} and C_{OUT} should be returned with a minimal path to these pins
D2	SDA	I ² C Data Line. Used for I ² C communication. If SDA is unused then tie pin to either AGND or PGND.
D3, D4	SW2	Switching Node 2. Connect to inductor L1
E2	PG	Power Good. This is an open-drain output and normally High Z. An external pull-up resistor from VOUT can be used to generate a logic HIGH. PG is pulled LOW if output falls out of regulation due to current overload or if thermal protection threshold is exceeded. If EN is LOW, PG is high impedance
B2	SCL	I ² C Clock Line. Used for I ² C communication. If SCL is unused then tie pin to either AGND or PGND.
E3, E4	VOUT	Output Voltage. Buck-Boost Output. Connect to output load and COUT

1. Refer to Layout Recommendation section located near the end of the datasheet.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$, Unless otherwise specified)

Symbol	Paran	neter	Min.	Max.	Unit
PVIN/AVIN	PVIN/AVIN Voltage		-0.3	6.5	V
VOUT	VOUT Voltage		-0.3	6.5	V
SW1, SW2	SW Nodes Voltage			7.0	V
	Other Pins		-0.3	6.5	V
500	Electrostatic Discharge Protection Level	ectrostatic Discharge Protection Level Human Body Model per JESD22-A114		00	
ESD	Charged Device Model per JESD22-C101		1000		V
TJ	Junction Temperature			+150	°C
T _{STG}	Storage Temperature		-65	+150	°C
ΤL	Lead Soldering Temperature, 10 Seconds			+260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
PVIN	Supply Voltage Range	2.5		5.5	V
I _{OUT}	Output Current (Note 2)	0		2.5	А
L	Inductor (Note 3)		1		μH
C _{OUT}	Output Capacitance (Note 3)		47		μF
T _A	Operating Ambient Temperature	-40		+85	°C
TJ	Operating Junction Temperature	-40		+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability. 2. Maximum current may be limited by the thermal conditions of the end application, PCB layout, and external component selection in addition

to the device's thermal properties. Refer to the Application Information and Application Guidelines sections for more information.

3. Refer to the Application Guidelines section for details on external component selection.

THERMAL PROPERTIES (Note 4, 5)

Symbol	Parameter	Min.	Тур.	Max.	Unit
θJA	Junction-to-Ambient Thermal Resistance		66		°C/W

4. Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four- layer 2s2p with vias JEDEC class boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature TJ(max) at a given ambient temperature ${\sf T}_{\sf A}.$ 5. See Thermal Considerations in the Application Information section.

ELECTRICAL CHARACTERISTICS (Note 6, 7)

Minimum and maximum values are at PVIN = AVIN = 2.5 V to 5.5 V, T_A = -40°C to +85°C. Typical values are at T_A = 25°C, PVIN = AVIN = V_{EN} = 3.6 V, VOUT = 3.4 V.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
POWER SUPP	PLIES			-		
l _Q	Quiescent Current	PFM Mode, I _{OUT} = 0 mA (Note 8)		24		μΑ
		PT Mode, I _{OUT} = 0 mA		27		
I _{SD}	Shutdown Supply Current	EN = GND, PVIN = 3.6 V		0.5	5.0	μA
V _{UVLO}	Under-Voltage Lockout Threshold	Falling PVIN	1.95	2.00	2.05	V
V _{UVHYST}	Under-Voltage Lockout Hysteresis			200		mV
EN, SDA, SCL						
V _{IH}	HIGH Level Input Voltage		1.1			V
V _{IL}	LOW Level Input Voltage				0.4	V
I _{IN}	Input Bias Current Into Pin	Input Tied to GND or PVIN		0.01	1.00	μA
G				-		
V _{PG}	PG LOW	I _{PG} = 5 mA			0.4	V
I _{PG_LK}	PG Leakage Current	V _{PG} = 5 V			1	μA
WITCHING						
f _{SW}	Switching Frequency	$PVIN = 3.6 \text{ V}, \text{ T}_{\text{A}} = 25^{\circ}\text{C}$	1.6	1.8	2.0	MHz
I _{p_LIM}	Peak PMOS Current Limit	PVIN = 3.6 V	4.6	5.2	5.9	Α
						•

Vout_acc	DC Output Voltage Accuracy	PVIN = 3.6 V, Forced PWM, I _{OUT} = 0 mA, VOUT = 3.4 V	3.366	3.400	3.434	V
		PVIN = 3.6 V, PFM Mode, I _{OUT} = 0 mA, VOUT = 3.4 V	3.366	3.475	3.563	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

 Refer to Typical Characteristics waveforms/graphs for Closed–Loop data and its variation with input voltage and ambient temperature. Electrical Characteristics reflects Open–Loop steady state data. System Characteristics reflects both steady state and dynamic Close–Loop data associated with the recommended external components.

7. Minimum and Maximum limits are verified by design, test, or statistical analysis. Typical (Typ.) values are not tested, but represent the parametric norm. 8. Device is not switching.

SYSTEM CHARACTERISTICS

The following table is verified by design and bench test while using circuit of Figure 1 with the recommended external components. Typical values are at $T_A = 25^{\circ}$ C, PVIN = AVIN = $V_{EN} = 3.6$ V, VOUT = 3.4 V. These parameters are not verified in production.

Symbol	Parameter		Min.	Тур.	Max.	Unit
V _{OUT_ACC}	Total Accuracy (Includes DC accuracy and load transient) (Note 9)			±5		%
ΔV_{OUT}	Load Regulation	I _{OUT} = 0.4 A to 2.5 A, PVIN = 3.6 V		-0.20		%/A
ΔV_{OUT}	Line Regulation	$3.0 \text{ V} \le \text{PVIN} \le 4.2 \text{ V}, \text{ I}_{OUT} = 1.5 \text{ A}$		-0.06		%/V
VOUT_RIPPLE	Ripple Voltage	PVIN = 4.2 V, VOUT = 3.4 V, I _{OUT} = 1 A, PWM Mode		4		mV
		PVIN = 3.6 V, VOUT = 3.4 V, I _{OUT} = 100 mA, PFM Mode		22		
		PVIN = 3.0 V, VOUT = 3.4 V, I _{OUT} = 1 A, PWM Mode		14		
η	Efficiency	PVIN = 3.0 V, VOUT = 3.4 V, I _{OUT} = 50 mA, PFM		90		%
		PVIN = 3.0 V, VOUT = 3.4 V, I _{OUT} = 500 mA, PWM		96		
		PVIN = 3.8 V, VOUT = 3.4 V, I _{OUT} = 50 mA, PFM		90		
		PVIN = 3.8 V, VOUT = 3.4 V, I _{OUT} = 600 mA, PWM		94		
		PVIN = 3.4 V, VOUT = 3.4 V, I _{OUT} = 300 mA, PWM		94		
T _{SS}	Soft-Start	EN HIGH to 95% of Target VOUT, I _{OUT} = 68 mA		260		μs
$\Delta VOUT_LOAD$	Load Transient	PVIN = 3.4 V, I _{OUT} = 0.5 A \Leftrightarrow 1 A, TR = TF = 1 μ s		±45		mV
		PVIN = 3.4 V, I _{OUT} = 0.5 A ⇔2.0 A, TR = TF = 1 μs, Pulse Width = 577 μs		±125]
$\Delta V \text{OUT_LINE}$	Line Transient	PVIN = 3.0 V ⇔ 3.6 V, TR = TF = 10 μs, I _{OUT} = 1 A		±60		mV

9. Load transient is from 0.5 A \Leftrightarrow 1 A.

TYPICAL CHARACTERISTICS

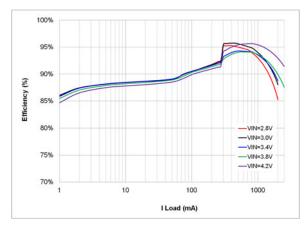


Figure 4. Efficiency vs. Load

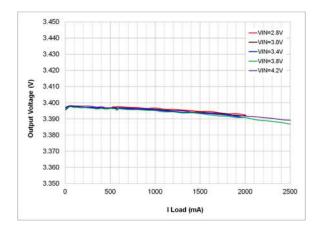
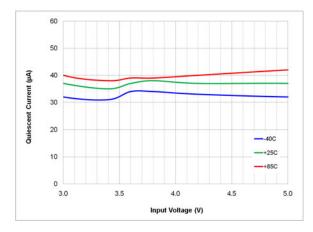
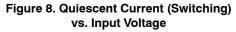


Figure 6. Output Regulation vs. Load, FPWM Mode





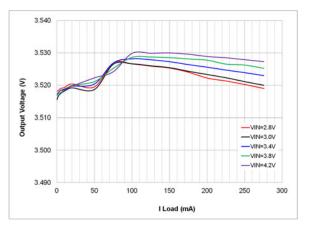


Figure 5. Output Regulation vs. Load

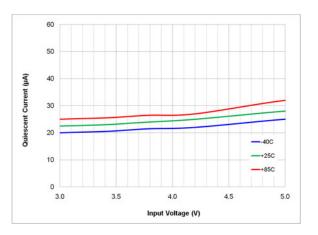


Figure 7. Quiescent Current (No Switching) vs. Input Voltage

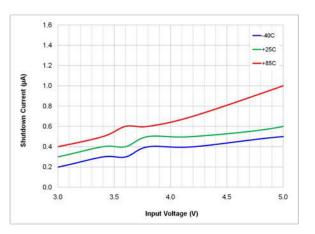


Figure 9. Shutdown Current vs. Input Voltage

TYPICAL CHARACTERISTICS

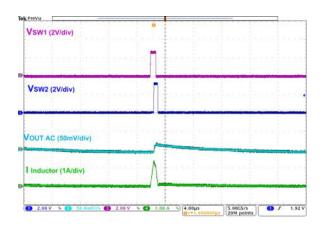


Figure 10. Output Ripple, VIN = 2.8 V, I_{OUT} = 20 mA, Boost Operation

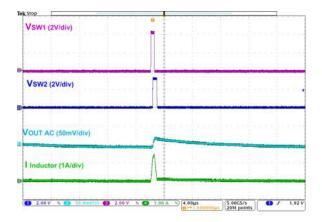


Figure 12. Output Ripple, VIN = 4.2 V, I_{OUT} = 20 mA, Buck Operation

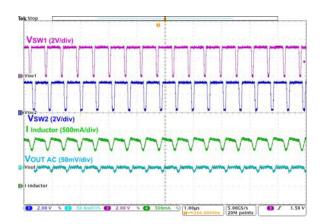


Figure 14. Output Ripple, VIN = 3.3 V, I_{OUT} = 1000 mA, Buck–Boost Operation

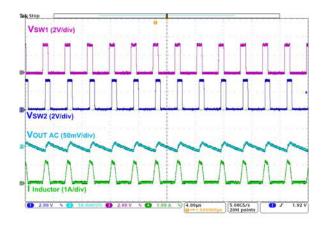


Figure 11. Output Ripple, VIN = 3.3 V, I_{OUT} = 200 mA, Buck-Boost Operation

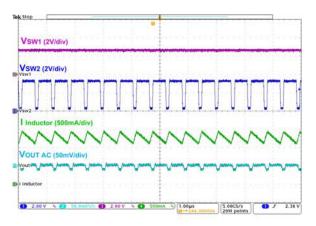


Figure 13. Output Ripple, VIN = 2.5 V, I_{OUT} = 1000 mA, Boost Operation

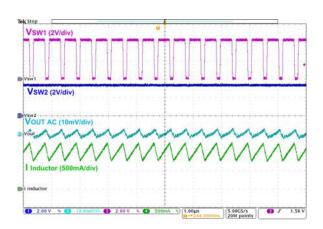


Figure 15. Output Ripple, VIN = 4.5 V, I_{OUT} = 1000 mA, Buck Operation

TYPICAL CHARACTERISTICS

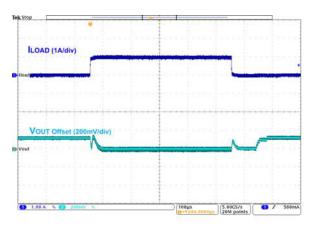


Figure 16. Load Transient, 0 mA ⇔ 1000 mA, 1 ms Edge, VIN = 3.60 V

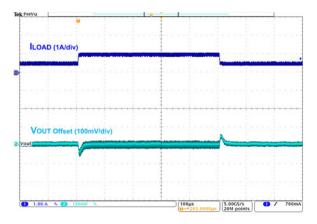


Figure 18. Load Transient, 500 mA ⇔ 1000 mA, 1 ms Edge, VIN = 3.40 V

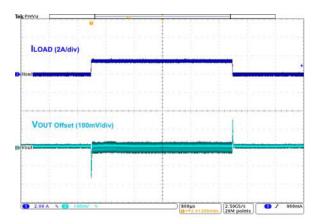


Figure 20. Load Transient, 0 mA ⇔ 1500 mA, 10 ms Edge, VIN = 2.80 V, PWM Mode

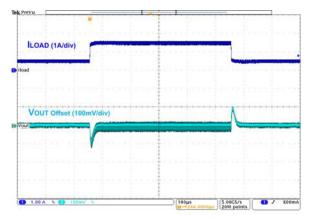


Figure 17. Load Transient, 500 mA ⇔ 1500 mA, 1 ms Edge, VIN = 3.60 V

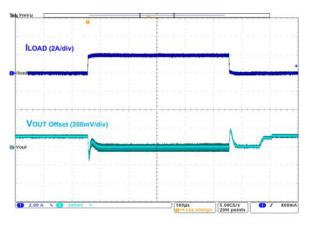
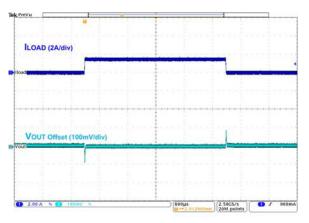
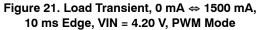


Figure 19. Load Transient, 0 mA ⇔ 2000 mA, 1 ms Edge, VIN = 3.60 V





TYPICAL CHARACTERISTICS

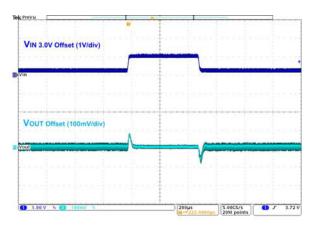


Figure 22. Line Transient, 3.2 ⇔ 4.0 VIN, 10 ms Edge, 1000 mA Load

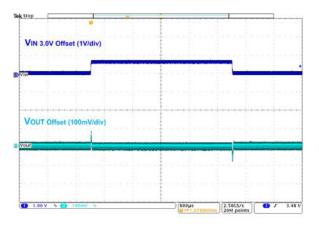


Figure 24. Line Transient, 3.0 ⇔ 3.6 VIN, 10 ms Edge, 1000 mA Load, PWM

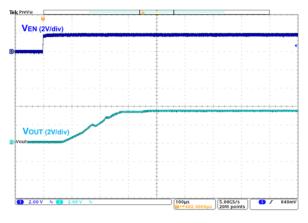


Figure 26. Startup, VIN = 3.6 V, I_{OUT} = 68 mA

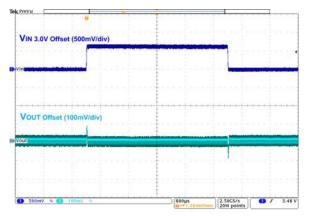


Figure 23. Line Transient, 3.0 ⇔ 3.6 VIN, 10 ms Edge, 1500 mA Load, PWM

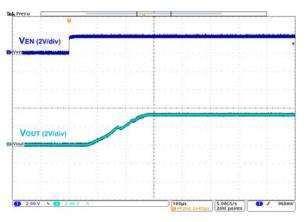
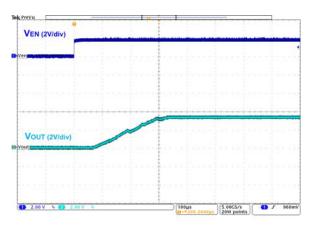
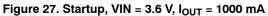


Figure 25. Startup, VIN = 3.6 V, I_{OUT} = 0 mA





TYPICAL CHARACTERISTICS

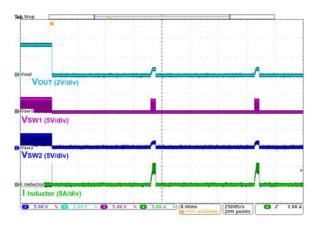


Figure 28. Short-Circuit Protection

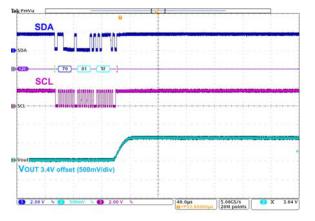


Figure 29. V_{OUT} Transition, 3.4 V \Leftrightarrow 4.0 V, 500 mA Load

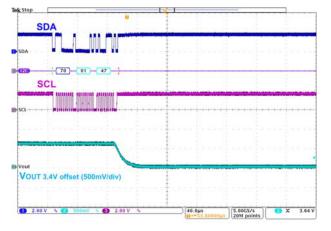


Figure 30. V_{OUT} Transition, 4.0 V \Leftrightarrow 3.4 V, 500 mA Load

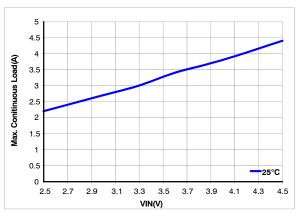


Figure 31. Typical Maximum Continuous Load vs. Input Voltage, V_{OUT}= 3.4 V, 25°C

APPLICATION INFORMATION

Functional Description

FAN49103 is a fully integrated synchronous, full bridge DC–DC converter that can operate in buck operation (during high PVIN), boost operation (for low PVIN) and a combination of buck–boost operation when PVIN is close to the target VOUT value. The PWM/PFM controller switches automatically and seamlessly between buck, buck–boost and boost modes.

The FAN49103 uses a four–switch operation during each switching period when in the buck–boost mode. Mode operation is as follows: referring to the power drive stage shown in Figure 32 if PVIN is greater than target VOUT, then the converter is in buck mode: Q3 is ON and Q4 is OFF continuously leaving Q1, Q2 to operate as a current-mode controlled PWM converter. If PVIN is lower than target VOUT then the converter is in boost mode with Q1 ON and Q2 OFF continuously, while leaving Q3, Q4 to operate as a current-mode boost converter. When PVIN is near VOUT, the converter goes into a 3-phase operation in which combines a buck phase, a boost phase and a reset phase; all switches are switching to maintain an average inductor volt-second balance.

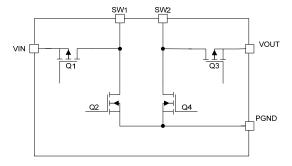


Figure 32. Simplified Block Diagram

PFM/PWM Mode

The FAN49103 uses a current-mode modulator to achieve smooth transitions between PWM and PFM operation. In Pulsed Frequency Modulation (PFM), frequency is reduced to maintain high efficiency. During PFM operation, the converter positions the output voltage typically 75 mV higher than the nominal output voltage during PWM operation, allowing additional headroom for voltage drop during a load transient from light to heavy load. As the load increased from light loads, the converter enters PWM operation typically at 300 mA of current load. The converter switching frequency is typically 1.8 MHz during PWM operation for moderate to heavy load currents.

PT (Pass-Through) Mode

In Pass-Through mode, all of the switches are not switching and VOUT tracks PVIN (VOUT = PVIN – I_{OUT} × (Q1_{RDSON} + Q3_{RDSON} + L_{DCR}). In PT mode only Over-Temperature (OTP) and Under Voltage Lockout (UVLO) protection circuits are activated. There is no Over-Current Protection (OCP) in PT mode.

Shutdown and Startup

When the EN pin is LOW, the IC is in Shutdown mode and non-essential internal circuits are off. In this state, I²C can be written to or read from. During shutdown, VOUT is isolated from PVIN. Raising EN pin activates the device and begins the soft-start cycle. During soft-start, the modulator's internal reference is ramped slowly to minimize surge currents on the input and prevent overshoot of the output voltage. If VOUT fails to reach target VOUT value after 1 ms, a FAULT condition is declared.

Over-Temperature (OTP)

The regulator shuts down when the die temperature exceeds 150°C. Restart occurs when the IC has cooled by approximately 20°C.

Output Discharge

When the regulator is disabled and driving the EN pin LOW, a 230 Ω internal resistor is activated between VOUT and GND. The Output Discharge is not activated during a FAULT state condition.

Over-Current Protection (OCP)

If the peak current limit is activated for a typical 700 μ s, a FAULT state is generated, so that the IC protects itself as well as external components and load.

FAULT State

The regulator enters the FAULT state under any of the following conditions:

- VOUT fails to achieve the voltage required after soft-start
- Peak current limit triggers
- OTP or UVLO are triggered

Once a FAULT is triggered, the regulator stops switching and presents a high-impedance path between PVIN and VOUT. After waiting 30 ms, a restart is attempted.

Power Good

PG, an open-drain output, is LOW during FAULT state and HIGH for Power Good.

The PG pin is provided for signaling the system when the regulator has successfully completed soft-start and no FAULTs have occurred. PG pin also functions as a warning flag for high die temperature and overload conditions.

- PG is released HIGH when the soft-start sequence is successfully completed
- PG is pulled LOW when a FAULT is declared. Any FAULT condition causes PG to be de-asserted

Thermal Considerations

F

For best performance, the die temperature and the power dissipated should be kept at moderate values. The maximum power dissipated can be evaluated based on the following relationship:

$$P_{D(max)} = \left\{ \frac{T_{J(max)} - T_{A}}{\Theta_{JA}} \right\}$$

where $T_{J(max)}$ is the maximum allowable junction temperature of the die; T_A is the ambient operating temperature; and θ_{JA} is dependent on the surrounding PCB layout and can be improved by providing a heat sink of surrounding copper ground.

The addition of backside copper with through-holes, stiffeners, and other enhancements can help reduce θ_{JA} . The heat contributed by the dissipation of devices nearby must be included in design considerations. Following the layout recommendation may lower the θ_{JA} .

I²C Interface

The FAN49103's serial interface is compatible with Standard, Fast, Fast Plus, and HS Mode I^2C -Bus specifications. The SCL line is an input and its SDA line is a bi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and when signaling ACK. All data is shifted in MSB (bit 7) first.

I²C Slave Address

In hex notation, the slave address assumes a 0 LS Bit. The hex slave address is 8h'E0 (7h'70) for FAN49103AUC340X. See Ordering information for other address options.

Table 1. I²C SLAVE ADDRESS

				Bi	ts			
Hex	7	6	5	4	3	2	1	0
E0	1	1	1	0	0	0	0	R/W

Bus Timing

As shown in Figure 33, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the

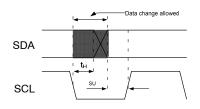


Figure 33. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCL HIGH. A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCL HIGH, as shown in Figure 34.

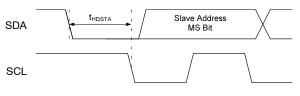
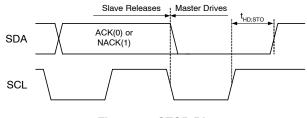
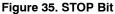


Figure 34. START Bit

A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 35.





During a read from the FAN49103, the master issues a REPEATED START after sending the register address, and before resending the slave address. The REPEATED START is a 1 to 0 transition on SDA while SCL is HIGH, as shown in Figure 36.

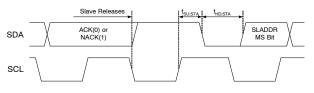


Figure 36. REPEATED START Bit

High-Speed (HS) Mode

The protocols for High–Speed (HS), Low–Speed (LS), and Fast–Speed (FS) Modes are identical; except the bus speed for HS mode is 3.4 MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a START condition. The master code is sent in Fast or Fast–Plus Mode (less than 1 MHz clock); slaves do not ACK this transmission.

The master generates a REPEATED START condition (Figure 34) that causes all slaves on the bus to switch to HS Mode. The master then sends I2C packets, as described above, using the HS Mode clock rate and timing.

The bus remains in HS Mode until a STOP bit (Figure 35) is sent by the master. While in HS Mode, packets are separated by REPEATED START conditions (Figure 36).

Read and Write Transactions

The following figures outline the sequences for data read and write. Bus control is signified by the shading of the packet, defined as

Master Drives Bus		
and		
Slave Drives Bus		

All addresses and data are MSB first.

Symbol	Definition
R	REPEATED START, see Figure 36
Р	STOP, see Figure 35
S	START, see Figure 34
A	ACK. The slave drives SDA to 0 to acknowledge the preceding packet
А	NACK. The slave sends a 1 to NACK the preceding packet
R	REPEATED START, see Figure 36
Р	STOP, see Figure 35



Figure 37. Write Transaction

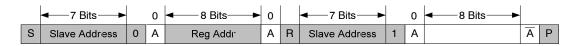


Figure 38. Read Transaction

Register Description

Table 3. REGISTER TABLE

Hex Address	Name	Function
00	SOFT-RESET	Resets all registers to default values
01	VOUT_REF	Set the target regulation point of VOUT
02	CONTROL	PT and MODE control
40	Manufacturer_ID	Read-only register identifies vendor and device type
41	Device_ID	Read-only register identifies die ID

BIT DEFINITIONS

The following table defines the operation of each register bit. Bold indicates power-on default values.

Bit	Name	Value			Descripti	on
OFT-RESET	w		REGISTI	ER ADDRESS: 00)	
7:1	Reserved	0000000				
0	Soft_reset	0	Write 1 to re	set all registers.		
OUT_REF	R/W		REGISTI	ER ADDRESS: 01		
7	Reserved	0				
6:0 Ref_dac_code 0000000 Sets the target regulation point for V0 zeroes. When changing the VOUT ta ing 00h. If the default VOUT voltage grammed to the non-reserved equiva				OUT target, do oltage must be l equivalent valu	not write the Reserved values, incluc written, the device must be pro- ue.	
			HEX	VOUT	HEX	VOUT
			00 – 2E	Reserved	47	3.400
			2F	2.800	48	3.425
			30	2.825	49	3.450
			31	2.850	4A	3.475
			32	2.875	4B	3.500
			33	2.900	4C	3.525
			34	2.925	4D	3.550
			35	2.950	4E	3.575
			36	2.975	4F	3.600
			37	3.000	50	3.625
			38	3.025	51	3.650
			39	3.050	52	3.675
			ЗA	3.075	53	3.700
			3B	3.100	54	3.725
			3C	3.125	55	3.750
			3D	3.150	56	3.775
			3E	3.175	57	3.800
			3F	3.200	58	3.825
			40	3.225	59	3.850
			41	3.250	5A	3.875
			42	3.275	5B	3.900
			43	3.300	5C	3.925
			44	3.325	5D	3.950
			45	3.350	5E	3.975
			46	3.375	5F 60 – 7F	4 Reserved
ONTROL	R/W		REGISTI	ER ADDRESS: 02	2	
7:4	Reserved	0000				
3	i2c_pt_in	0	Enables Pa	ss–Through mode	Э.	
			Code	Mode		
			0		utput (Boost, Bi	ick or Buck–Boost)
			1	Pass-Throug		
2	i2c_mode_in	0	Enables Fo	rced PWM mode,	as long as Pas	s-Through is not enabled.
			Code	Mode		
			0	Auto PWM –	PFM mode bas	sed on load
			1		I mode enabled	

1:0	Reserved	00	
MANUFACT	URER_ID R		REGISTER ADDRESS: 40
7:0	Manufacture_ID	10000011	
DEVICE_ID R			REGISTER ADDRESS: 41
7:0	Device_ID	00000111	

APPLICATION GUIDELINES

Reference Designator	esignator Description		Part Number
L	1 μ H, Isat(max) = 4.2 A, 36 m Ω (max), 2016	1	Cyntec HTEH20161T-1R0MSR
C _{OUT}	47 μF (x2), 6.3 V, X5R, 1608	2	Murata GRM188R60J476ME15
C _{IN}	22 μF, 10 V, X5R, 1608	1	Murata GRM187R61A226ME15

Table 4. RECOMMENDED EXTERNAL COMPONENTS

Alternative External Components

It is recommended to use the external components in Table 4. Alternative components that are suitable for a design's specific requirements must also meet the IC's requirements for proper device operation.

De-rating factors should be taken into consideration to ensure selected components meet minimum requirements.

Output Capacitor (COUT)

As shown in the recommended layout, C_{OUT} must connect to the VOUT pin with the lowest impedance trace possible. Additionally, C_{OUT} must connect to the GND pin with the lowest impedance possible.

Smaller-than-recommended value output capacitors may be used for applications with reduced load current requirements. When selecting capacitors for minimal solution size, it must be noted that the effective capacitance (C_{FFF}) of small, high-value, ceramic capacitors will decrease as bias voltage increases. The effects of Bias Voltage (DC Bias Characteristics), Tolerance, and

Table 6. EFFECTIVE CAPACITANCE VERSUS PART NUMBER

Temperature should be included when determining a component's effective capacitance.

The FAN49103 is guaranteed for stable operation with no less than the minimum effective output capacitance values shown in Table 5.

Maximum Load Current	Inductor (μH)	Required Minimum Effective Output Capacitance (μF)
<u><</u> 2000 mA	1.0	15
	0.47	9
<u>≺</u> 1500 mA	1.0	12
<u>≤</u> 1000 mA	1.0	9
<u><</u> 600 mA	1.0	7
<u><</u> 500 mA	1.0	6

Table 5. REQUIRED MINIMUM EFFECTIVE OUTPUT
CAPACITANCE VERSUS MAXIMUM LOAD

	Nominal	Deting	Tel

PN	Size (mm) LW x H	Nominal Value (μF)	Rating (V)	Tol. (%)	Bias (V)	Effective Capacitance (μF) Due to Bias, Temperature and Tolerance
Murata GRM188R60J476ME15	1608 x 1.0	47	6.3	20	3.4	8.5
Murata GRM187R61A226ME15	1608 x 0.8	22	10	20	3.4	6.3
					5	4.2
Murata GRM188R61A106KE69	1608 x 1.0	10	10	10	3.4	3.2
					5	2.3

Input Capacitor (C_{IN})

As shown in the recommended layout, CIN must connect to the PVIN pin with the lowest impedance trace possible. Additionally, CIN must connect to the GND pin with the lowest impedance possible.

The FAN49103 is guaranteed for stable operation with a minimum effective capacitance of 2 µF. It is recommended to use a high quality input capacitor rated at 10 µF nominal or greater. Additional capacitance is required when the FAN49103's power source is not located close to the device.

Inductor (L)

As shown in the recommended layout, the inductor (L) must connect to the SW1 and SW2 pins with the lowest impedance trace possible.

The recommended nominal inductance value is 1.0 µH. A value of 0.47 µH can be used, but higher peak currents should be expected.

The FAN49103 employs peak current limiting, and the peak inductor current can reach IP LIM before limiting, therefore current saturation should be considered when choosing an inductor.

Description	Part Number
1 μH, Isat(max) = 5.0 A, 25 mΩ (max), 2520	Cyntec HTEH20161T-1R0MSR
1 μH, Isat(max) = 5.3 A, 23 mΩ (max), 2520	Semco CIGT252010TM1R0ML

LAYOUT RECOMMENDATIONS

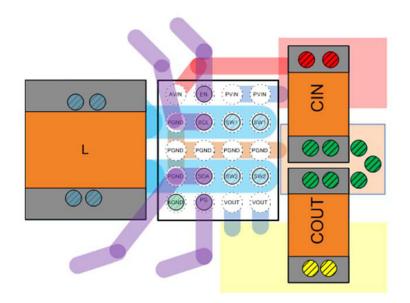
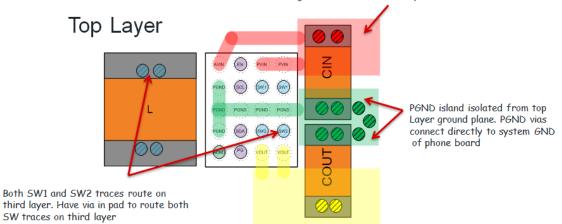
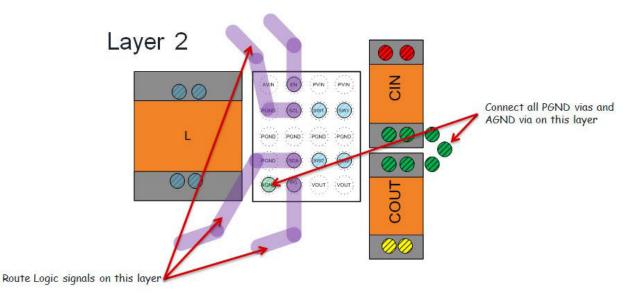


Figure 39. Component Placement and Routing for FAN49103

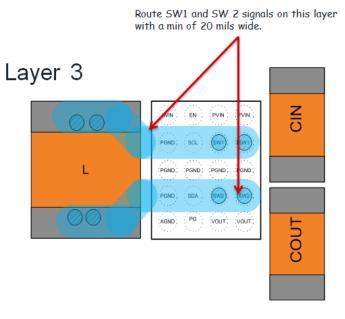


 $\ensuremath{\mathsf{VIN}}\xspace$ via bring $\ensuremath{\mathsf{VIN}}\xspace$ trace from inner layer

Figure 40. Top Layer Routing for FAN49103









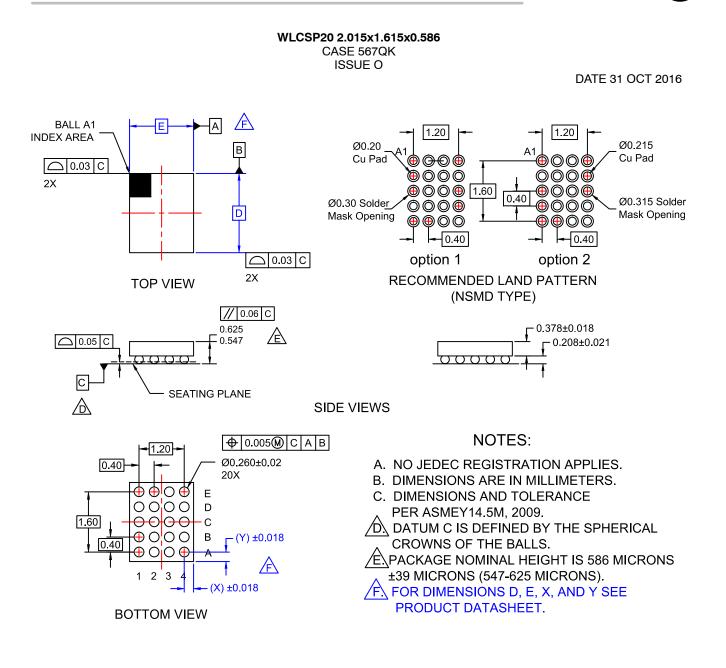
PHYSICAL DIMENSIONS

This table information applies to the Package drawing on the following page.

Product	D	E	Х	Y
FAN49103AUC340X	2.015 ± 0.030	1.615 ±0.030	0.2075	0.2075
FAN49103AUC330X	2.015 ± 0.030	1.615 ±0.030	0.2075	0.2075

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